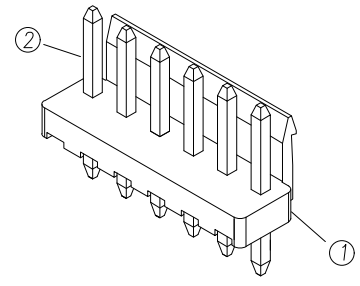
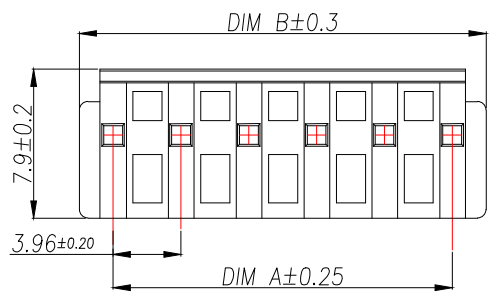


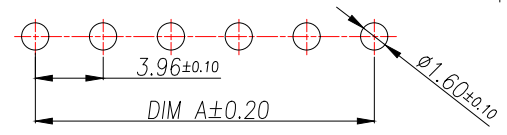
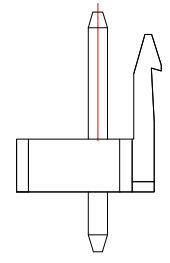
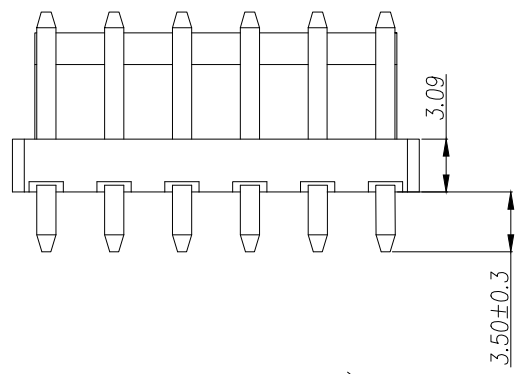
REV.	Q'TY	ECN. NO.	APR.	DATE

PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



- 技术要求:
- 1、塑件材料:PA66 (UL-94V-0)
 - 2、接触件:黄铜镀锡
 - 3、接触电阻: ≤20mΩ
 - 4、绝缘电阻: ≥1000MΩ
 - 5、额定电压:250V AC DC
 - 6、额定电流:3.0A AC DC
 - 7、耐压:能承受1000V AC/Min ute
 - 8、工作温度:-25°~+85°
 - 9、可焊性试验:浸锡面积≥95%温度235⁺⁵₀,时间2.5±0.5秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B
XY-VH3.96-2A11	2	3.96	7.92
XY-VH3.96-3A11	3	7.92	11.88
XY-VH3.96-4A11	4	11.88	15.84
XY-VH3.96-5A11	5	15.84	19.80
XY-VH3.96-6A11	6	19.80	23.76
XY-VH3.96-7A11	7	23.76	27.72
XY-VH3.96-8A11	8	27.72	31.68
XY-VH3.96-9A11	9	31.68	35.64
XY-VH3.96-10A11	10	35.64	39.60
XY-VH3.96-11A11	11	39.60	43.56
XY-VH3.96-12A11	12	43.56	47.52
XY-VH3.96-13A11	13	47.52	51.48
...
XY-VH3.96-20A11	20	(20-1)*3.96	20*3.96



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再 镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*± 5°	APR.	Alex	TITLE: WAFER 3.96mm H3.0mm 180° DIP
.XX±0.25	.X.*± 3°	CHK.	Jack	DWG NO. XY-VH3.96-NA11
.XXX±0.15	.XX.*± 1°	DRA.	Can	PROJ. CUSTOMER DRAWING
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	